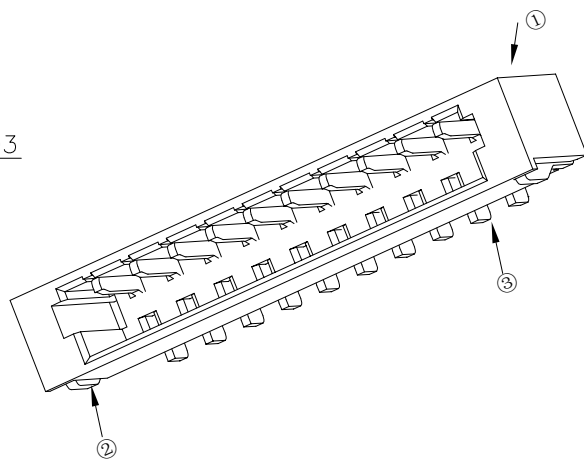
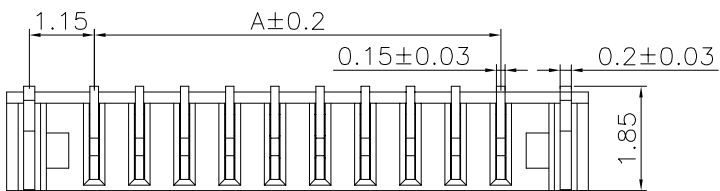
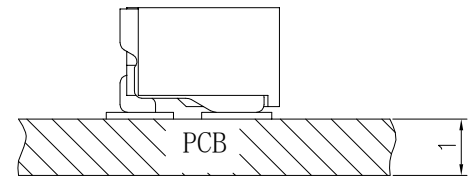
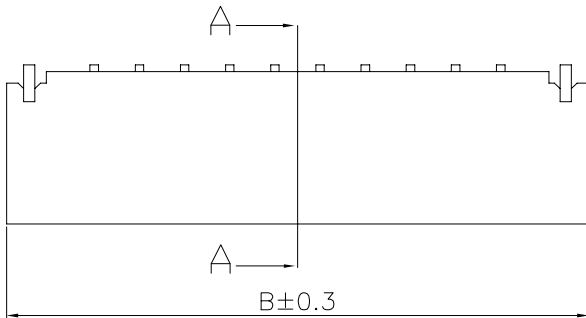
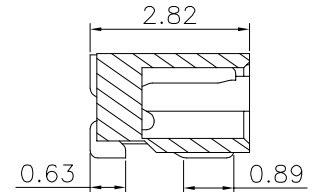
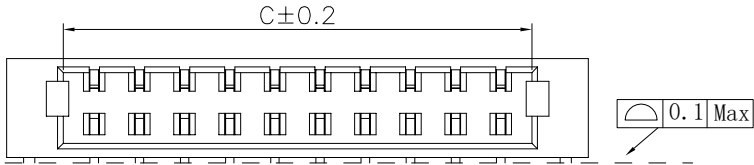


The product using material and processing must conform to the "WI-PZ-142"HSF technical standard control requirements

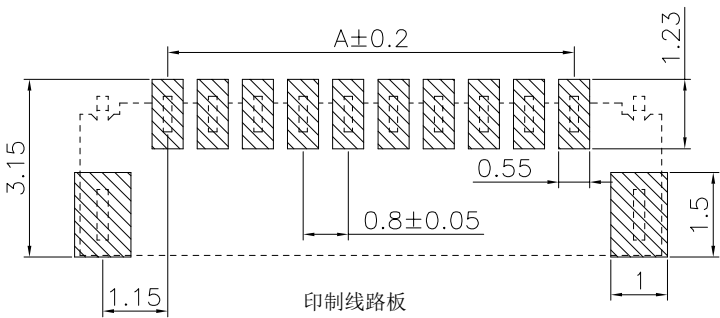
RoHS+HF

截面 A-A



NOTE:
 1.MATERIAL SPECIFICATION:
 1-1.HOUSING:LCP E130i UL94V-0
 1-2.CONTACTS:COPPER ALLOY
 1-3.SHELL:COPPER ALLOY
 2.PLATING SPECIFICATION:
 2-1.CONTACTS:
 TIN PLATED OVER Or all AU G/F.
 3.MECHANICAL PERFORMANCE:
 3-1.REMOVAL FORCE: 2.5kgf MIN
 4.ELECTRICAL PERFORMANCE:
 4-1. RATED CURRENT : 0.5A AC,DC
 RATED VOLTAGE : 50V AC/DC
 4-2.INSULATION RESISTANCE: 500V AC
 CONTACT RESISTANCE : 20mΩ(MAX.)
 4-3.WITHSTANDING VOLTAGE: 100MΩ min
 5.ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -25°C~+85°C.
 6.HUMIDITY LEVEL:LEVEL 2
 7.PACKAGE SPEC: REEL

Series No: **△A1** D0801 W 9-1 XX 2 X X 0
 Connector: W-WAFER
 Angle: 9-90°
 0-180°
 Row No: 1-SINGLE ROW
 Pin Q'PY: 02~20
 Color: A-BLACK, K-WHITE, M-BEIGE
 Plating: A-ALL AU G/F, C-BRIGHT TIN, D-MATTE Tin
 Termpoint: 2-SMT



印制线路板

NO	物料名称	规格型号	数量(PCS)	材质	镀涂
①	基座	0.8	1	LCPE130i	本色
②	焊片	0.8	2	磷铜	锡
③	插针	0.8	2~20	磷铜	锡

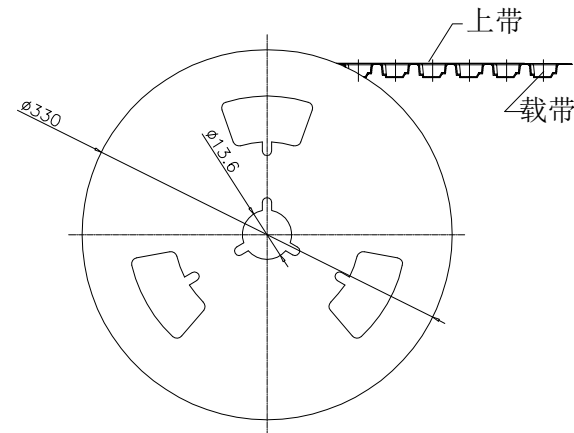
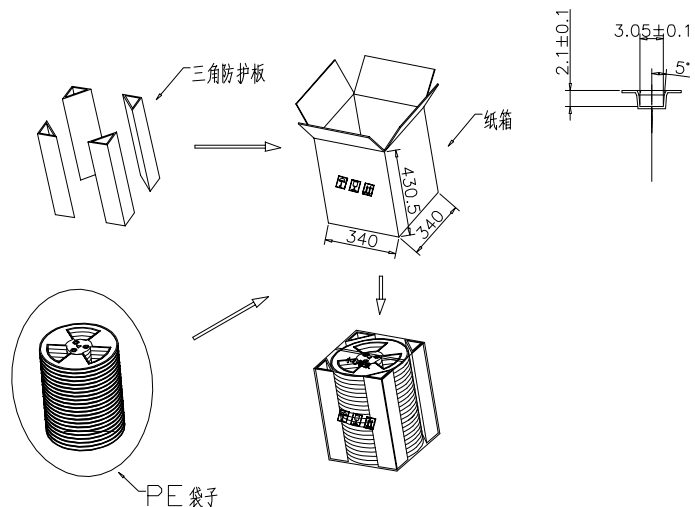
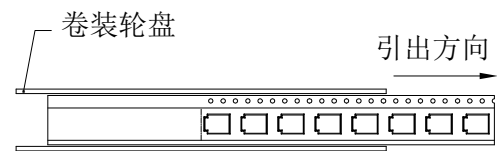
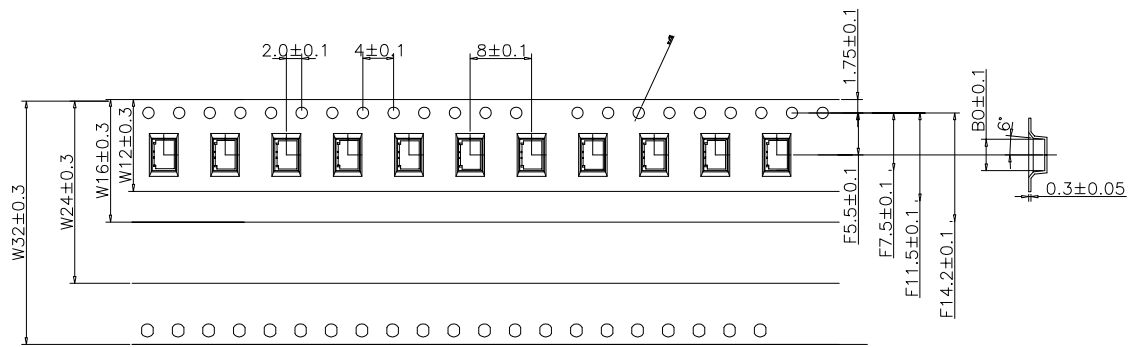
Circuits	Dimensions (mm)			Circuits	Dimensions (mm)		
	A	B	C		A	B	C
02	0.8	3.90	1.90	12	8.80	11.90	9.90
03	1.6	4.70	2.70	13	9.60	12.70	10.70
04	2.4	5.50	3.50	14	10.40	13.50	11.50
05	3.2	6.30	4.30	15	11.20	14.30	12.30
06	4.0	7.10	5.10	16	12.00	15.10	13.10
07	4.8	7.90	5.90	17	12.80	15.90	13.90
08	5.6	8.70	6.70	18	13.60	16.70	14.70
09	6.4	9.50	7.50	19	14.40	17.50	15.50
10	7.2	10.30	8.30	20	15.20	18.30	16.30
11	8.0	11.10	9.10				

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES	SCALE:	NAME	DATE	PART.NO:	DWG.NO:
A0	NEW RELEASE	21.01.13	LINEAR	1:1	Wang_jr	23.09.12	D0801W9-1XX2XX0	ENDE05
A1	PART NUMBER RENEWAL	23.09.12	ANGLES		Ding_bo	23.09.12		
			0.00±0.25		LX_HOU	23.09.12		
			X'±3'					
			X'X' ±2'					
			UNIT:mm				TITLE: Pitch 0.80mm single row 90° horizontal SMT type Wafer	
			SIZE: A4				REV: A1	SHEET: 1/2



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RoHS+HF

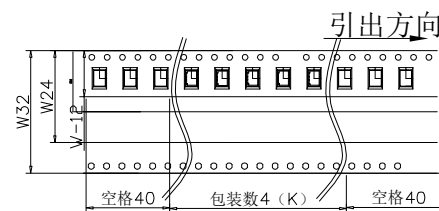


1. 上带剥离力:



2. 带子预空格:

A	15°~0°
F	20°~70°(q)



3. 载带材料规格: PS 白色料抗静电, 厚度 0.30mm.

Circuits	载带尺寸			Circuits	载带尺寸			卷装包装明细表			
	W	B0	F		A	B	C	PIN位	每卷包装数	每件盘数	每件数量
02	12.0	4.10	5.50					02-03P	4000(PCS)	30 (盘)	120(K)
3P	12.0	4.90	5.50					04-08P	4000(PCS)	20 (盘)	80(K)
4P	16.0	5.70	7.50					09-12P	4000(PCS)	14 (盘)	56(K)
5P	16.0	6.50	7.50								
6P	16.0	7.30	7.50								
7P	16.0	8.10	7.50								
8P	16.0	8.90	7.50								
9P	24.0	9.70	11.50								
10P	24.0	10.5	11.50								

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Technology Co., Ltd
A0	NEW RELEASE	21.01.13		LINEAR	ANGLES	APPROVED	Wang_jr	23.09.12	D0801W9-1XX2XX0	ENDE05	
A1	PART NUMBER RENEWAL	23.09.12		0.0±0.35	X'REF±6°	DESIGNER	Ding_bo	23.09.12	TITLE:		
				UNIT:mm	X'±3°	DRAWN	LX_HOU	23.09.12	Pitch 0.80mm single row 90° horizontal SMT type Wafer		
			SIZE: A4	0.000±0.10	X'X' ±2°				REV: A1	SHEET: 2/2	